

File No. 14836-9US AD/bns

Montréal, CANADA,

February 29, 2008

**UNITED STATES PATENT AND TRADEMARK OFFICE**

Application No : 10/532,627  
Filing Date : April 25, 2005  
Applicant : Microbridge Technologies Inc.  
Inventor : Leslie M. Landsberger et al.  
Title of Invention : METHOD FOR PRODUCING A PACKAGED INTEGRATED  
CIRCUIT  
Classification : 2822  
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**Mail Stop Amendment**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

USA

**RESPONSE AFTER FINAL**

Sir:

In response to the Office Action dated December 13, 2007 in connection with the above-identified Application, please consider the following:

**Amendments to the claims** begin on page 2 of this paper.

**Amendments to the specification** begin on page 8 of this paper.

**Amendments to the drawings** begin on page 11 of this paper.

**Remarks** begin on page 12 of this paper.

**An Appendix** including replacement drawing sheets is included after page 13 of this paper.